Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!

Contact us

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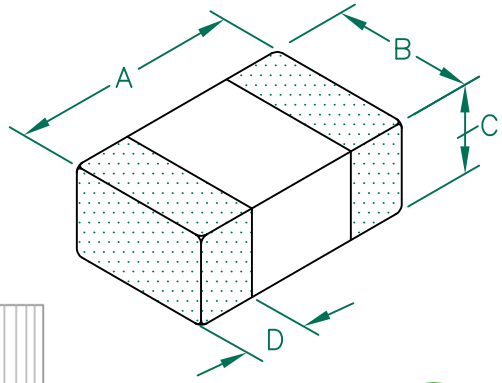
Email & Skype: info@chipsmall.com Web: www.chipsmall.com
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

CPI0805F2R2R-10

UNCONTROLLED DOCUMENT

PHYSICAL DIMENSIONS:

A	2.00 [.079]	±	0.20[.008]
B	1.25 [.049]	±	0.20[.008]
C	0.90 [.035]	±	0.10[.004]
D	0.50 [.020]	±	0.20[.008]

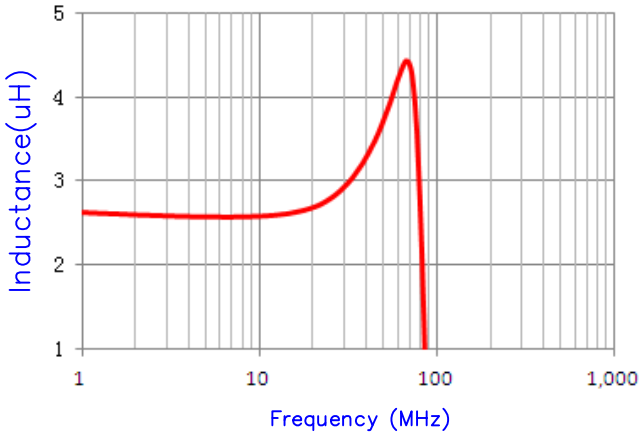


ELECTRICAL CHARACTERISTICS:

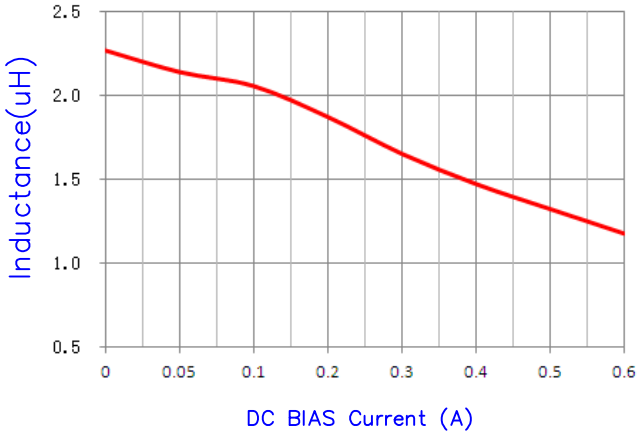
	L (μH) @ 1MHz ± 20%	DCR (Ω) ± 25%	I (Max)
Nom	2.2	0.25	
Min	1.8	0.1875	
Max	2.6	0.3125	600mA

NOTES: UNLESS OTHERWISE SPECIFIED
1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, 4000 PCS/REEL, PAPER TAPE.
2. TERMINATION FINISH IS 100% MATTE Sn OVER Ni.
3. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
4. I (MAX.) IS BASED ON THE MAXIMUM SUSTAINED CURRENT APPLIED WHILE MAINTAINING A MAXIMUM TEMPERATURE RISE OF 40°C OVER AMBIENT.
5. Operation Temperature TEMP: −55°C~+125°C. (INCLUDING SELF−HEATING)

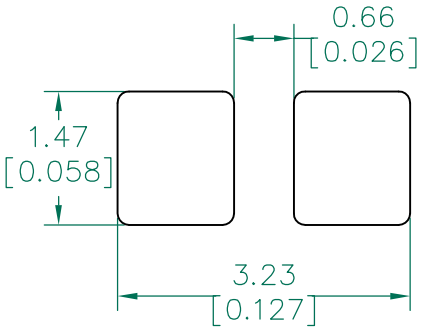
Ls vs Frequency



Ls vs DC BIAS Current

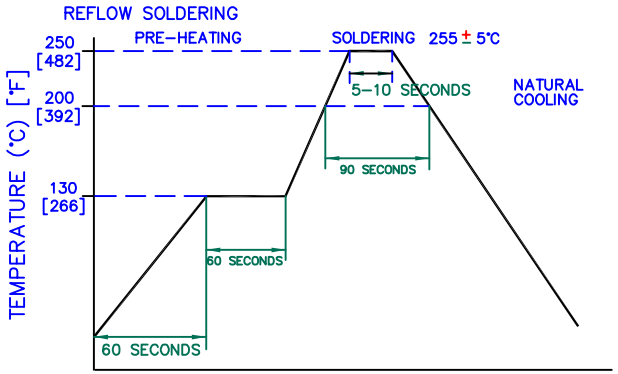


LAND PATTERNS FOR REFLOW SOLDERING



(For wave soldering. add 0.763 [0.030] to this dimension)

RECOMMENDED SOLDERING CONDITIONS



RoHS 2002/95/EC

DIMENSIONS ARE IN mm [INCHES].

REV	DESCRIPTION	DATE	INT
C	CHANGE PLASTIC TAPE TO PAPER TAPE	04/17/14	QU
B	UPDATE LAIRD LOGO AND NOTES 5	08/05/13	QU
A	ORIGINAL DRAFT	03/01/11	QU

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Laird

PROJECT/PART NUMBER:	REV	PART TYPE:	DRAWN BY:
CPI0805F2R2R−10	C	CO−FIRE	QU

DATE:	SCALE:	SHEET:
03/01/11	NTS	1 of 1

CAD # CPI0805F2R2R−10−A TOOL # −